<u>MOSFET</u> – Power, Single, N-Channel 40 V, 3.8 mΩ, 85 A

Features

- Small Footprint (3.3 x 3.3 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



ON Semiconductor®

www.onsemi.com

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX	
40 V	3.8 mΩ @ 10 V	85 A	
40 V	6 mΩ @ 4.5 V	A 68	

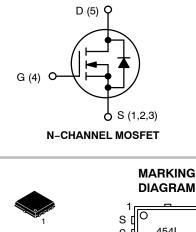


DIAGRAM D SE 454I D WDFN8 AYWW. S ΔD (µ8FL) G D h CASE 511AB 454L = Specific Device Code = Assembly Location Α Y = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 5 of this data sheet.

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Parameter			Symbol	Value	Unit	
Drain-to-Source Voltage			V _{DSS}	40	V	
Gate-to-Source Voltage			V _{GS}	±20	V	
Continuous Drain		$T_C = 25^{\circ}C$	۱ _D	85	А	
Current R _{θJC} (Notes 1, 3)	Steady State	T _C = 100°C		60		
Power Dissipation		$T_{C} = 25^{\circ}C$	PD	55	W	
R _{θJC} (Note 1)		$T_{C} = 100^{\circ}C$		27		
Continuous Drain	Steady State	$T_A = 25^{\circ}C$	۱ _D	20	А	
Current R _{θJA} (Notes 1, 2, 3)		T _A = 100°C		14		
Power Dissipation		$T_A = 25^{\circ}C$	PD	3.2	W	
R _{θJA} (Notes 1 & 2)		$T_A = 100^{\circ}C$		1.6		
Pulsed Drain Current	$T_A = 25^{\circ}C$, $t_p = 10 \ \mu s$		I _{DM}	520	А	
Operating Junction and Storage Temperature			T _J , T _{stg}	–55 to +175	°C	
Source Current (Body Diode)			۱ _S	61	А	
Single Pulse Drain-to-Source Avalanche Energy $(I_{L(pk)} = 5 A)$			E _{AS}	202	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	2.7	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	47	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

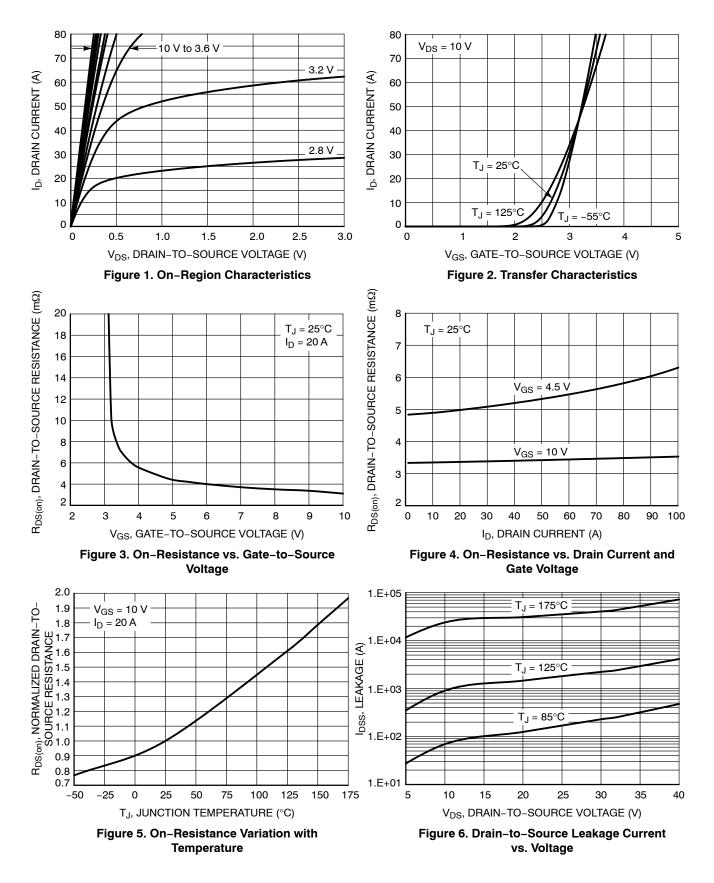
3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

ELECTRICAL CHARACTERISTICS (T_J = 25° C unless otherwise specified)

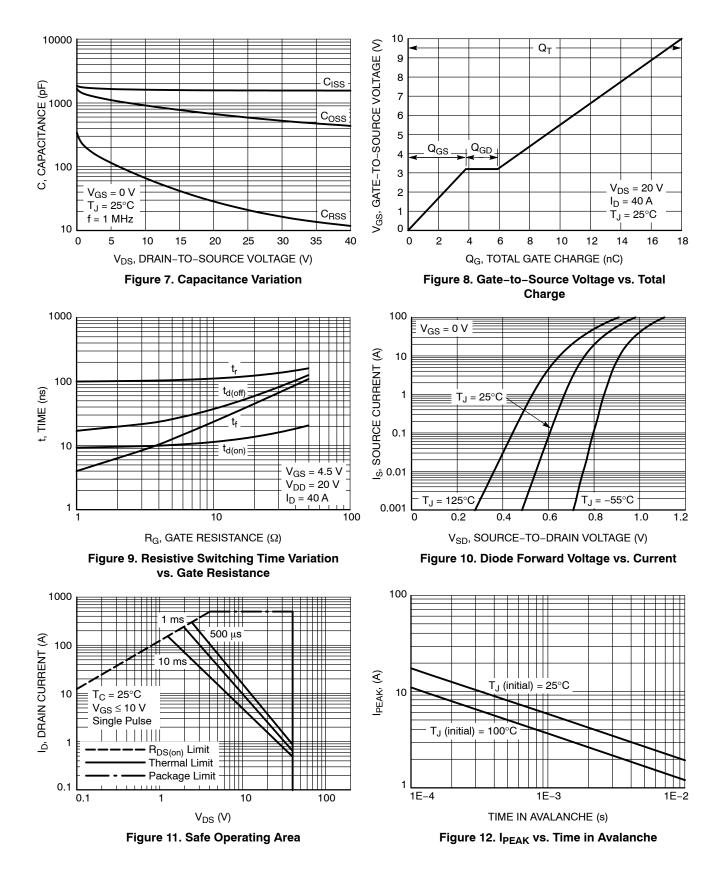
Parameter	Symbol	Test Condition		Min	Тур	Max	Unit	
OFF CHARACTERISTICS		• •		-	-			
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_D = 250 μ A		40			V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J				22		mV/°C	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	T _J = 25 °C			10		
		$V_{DS} = 40 V$ $T_{J} = 125^{\circ}C$				250	μΑ	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = 20 V				100	nA	
ON CHARACTERISTICS (Note 4)								
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}$, $I_D = 50 \ \mu A$		1.2	1.7	2.0	V	
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.1		mV/°C	
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V I _D = 20 A			3.2	3.8		
		V _{GS} = 4.5 V	I _D = 20 A		4.8	6	mΩ	
Forward Transconductance	9 _{FS}	V _{DS} = 15 V, I _D = 40 A			80		S	
Gate Resistance	R _G				1.4		Ω	
CHARGES AND CAPACITANCES		• •		-	-			
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			1600			
Output Capacitance	C _{OSS}				590		pF	
Reverse Transfer Capacitance	C _{RSS}				21			
Output Charge	Q _{OSS}	V_{GS} = 0 V, V_{DD} = 20 V			21		nC	
Total Gate Charge	Q _{G(TOT)}	V_{GS} = 10 V, V_{DS} = 20 V; I_{D} = 40 A			18			
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 20 V; I _D = 40 A			8.2		nC	
Threshold Gate Charge	Q _{G(TH)}				2			
Gate-to-Source Charge	Q _{GS}				3.8			
Gate-to-Drain Charge	Q _{GD}				2.1			
Plateau Voltage	V _{GP}				3.2		V	
SWITCHING CHARACTERISTICS (Note 5)		• •		-	-			
Turn-On Delay Time	t _{d(ON)}				9.3		- ns	
Rise Time	t _r	V _{GS} = 4.5 V, V _D	_s = 20 V,		100			
Turn-Off Delay Time	t _{d(OFF)}	$I_D = 40 \text{ A}, R_G$	= 2.5 Ω		17			
Fall Time	t _f	1			4		1	
DRAIN-SOURCE DIODE CHARACTERISTIC	cs	•			•		•	
Forward Diode Voltage	V _{SD}	$V_{GS} = 0 V.$	$T_J = 25^{\circ}C$		0.86	1.2	- v	
		V _{GS} = 0 V, I _S = 40 A	T _J = 125°C		0.75			
Reverse Recovery Time	t _{RR}				29			
Charge Time	t _a	V _{GS} = 0 V. dl _s /dt :	= 100 A/us.		14		ns	
Discharge Time	t _b	V_{GS} = 0 V, dI _S /dt = 100 A/µs, I _S = 40 A			15		1	
Reverse Recovery Charge	Q _{RR}				20		nC	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Pulse Test: pulse width $\leq 300 \ \mu$ s, duty cycle $\leq 2\%$. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

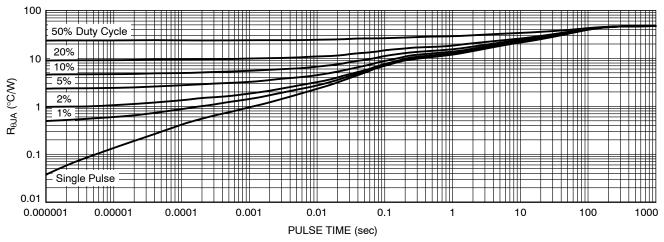


Figure 13. Thermal Characteristics

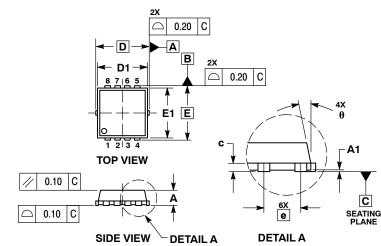
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTTFS5C454NLTAG	454L	WDFN8 (Pb-Free)	1500 / Tape & Reel
NTTFS5C454NLTWG	454L	WDFN8 (Pb-Free)	5000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

WDFN8 3.3x3.3, 0.65P CASE 511AB **ISSUE D**



8X С В 0.10 А 0.05 С e/2 4X Ā É2 E3 м ¥ D2 G

BOTTOM VIEW

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NOTES

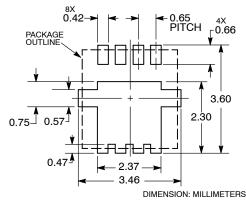
DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
CONTROLLING DIMENSION: MILLIMETERS.

3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH RRS.

PROTRUSIONS OR GATE BUF

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.75	0.80	0.028	0.030	0.031	
A1	0.00		0.05	0.000		0.002	
b	0.23	0.30	0.40	0.009	0.012	0.016	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D	3.30 BSC			0.130 BSC			
D1	2.95	3.05	3.15	0.116	0.120	0.124	
D2	1.98	2.11	2.24	0.078	0.083	0.088	
E	3.30 BSC			0.130 BSC			
E1	2.95	3.05	3.15	0.116	0.120	0.124	
E2	1.47	1.60	1.73	0.058	0.063	0.068	
E3	0.23	0.30	0.40	0.009	0.012	0.016	
е	0.65 BSC			0.026 BSC			
G	0.30	0.41	0.51	0.012	0.016	0.020	
к	0.65	0.80	0.95	0.026	0.032	0.037	
L	0.30	0.43	0.56	0.012	0.017	0.022	
L1	0.06	0.13	0.20	0.002	0.005	0.008	
М	1.40	1.50	1.60	0.055	0.059	0.063	
θ	0 °		12 °	0 °		12 °	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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